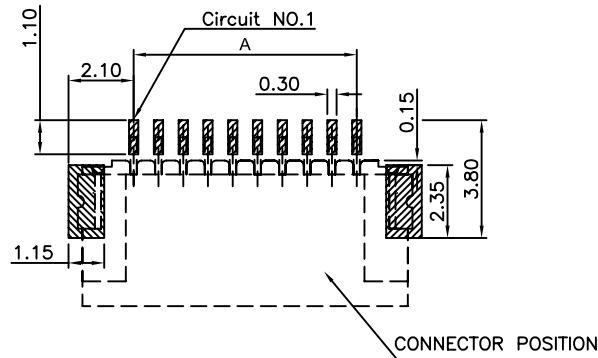
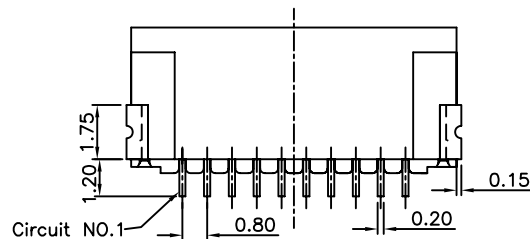
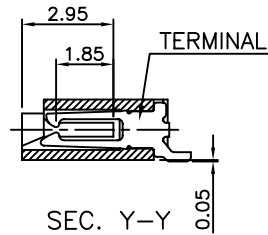
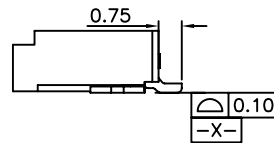
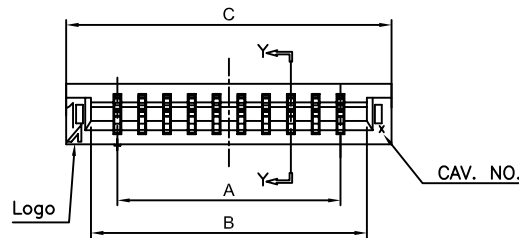


RECOMMENDED APPLICABLE FPC LAYOUT  
(THICKNESS:0.3±0.03)



PCB PATTERN LAYOUT



NOTES:

1. MATERIAL:

1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0

1.2 CONTACT: COPPER ALLOY

1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

50u" MIN. NICKEL UNDERPLATING OVERALL.

1: Gold Flash overall.

N: 120u" MIN. Pure Tin(MATT TIN) OVER ALL.

2.2 FITTING NAIL:

50u" MIN. NICKEL UNDERPLATING OVERALL.

1: Gold Flash overall.

N: 120u" MIN. Pure Tin(MATT TIN) OVER ALL.

3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4. SPEC. PLS. REFER TO SPEC-50634-XXXXX-XXX ▲

5. PACKAGING REFER TO EN-87057-XXXXX-TRP.

P/N LEGEND

50635-XXX X X-XXX

NO OF CKT

PACKING

0:TAPE & REEL

1:TUBE

PLATING

1:G/F OVER ALL(LEAD FREE)

N:MATT TIN(LEAD FREE)

XXX	Housing MAT.	Housing Color.	Halogen Free
001	HF PLASTIC	BLACK	<b>HF</b>

CKT	Dim A	Dim B	Dim C
6	4.00	5.70	7.30
10	7.20	8.90	10.50

一般公差 <b>TOLERANCES</b> X ±0.5    XI ±0.15 X ±0.25    XXX ±0.1 ANGLES    ±2°		<b>宏致電子股份有限公司</b> <b>Aces Electronic Co.,Ltd.</b>	
檢驗尺寸標示 <b>SYMBOLS</b> ⊕ ⊕ INDICATE CLASSIFICATION DIMENSION ⊕ MARK IS CRITICAL DIM. ⊕ MARK IS MAJOR DIM.	品名 (TITLE) 0.8 mm NON ZIF FPC CONN. SMT R/A TYPE	製圖 (DR) 11/05/07 SHM 審核 (CHKD) CARL	
	圖號 (DWG.NO) 50635-XXXXX-XXX	核准 (APPD) JASON	
表面處理 (FINISH)	比例 (SCALE) 4:1	單位 (UNITS) mm	張數 (SHEET) 1 OF 1 尺寸 (SIZE) A4 頁數 (REV) B